PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3645040

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yu-Ru Yang	11/20/2015
Huai-Tzu Chiang	11/20/2015
Sheng-Hao Lin	11/20/2015
Shih-Hsien Huang	11/27/2015
Chien-Hung Chen	11/20/2015
Chun-Yuan Wu	11/20/2015
Cheng-Tzung Tsai	11/20/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14960430

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562
Email: Patent.admin.uspto.cr@naipo.com
Correspondent Name: WINSTON HSU
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Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2604USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	12/06/2015

Total Attachments: 14

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:
SEMICONDUCTOR STRUCTURE

As the below named inventor, I hereby declare that:
This declaration is directed to:

☑ The attached application, or

☐ United States application number ________________ filed on ____________, or

☐ PCT international application number ________________ filed on ____________

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of

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(referred to as "ASSIGNEE"below) to I of the sum of One Dollar ($ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.
IN WINTNESS WHEREOF, I have hereunto set hand and seal this NOV 20 2015 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yu-Ru Yang** Date: NOV 20 2015

Signature: Yu-Ru Yang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Huai-Tzu Chiang** Date: NOV 20 2015

Signature: Huai Tzu Chiang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Sheng-Hao Lin** Date: NOV 20 2015

Signature: Shenghao Lin

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Shih-Hsien Huang** Date: NOV 2 7 2015

Signature: Shih-Hsien Huang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chien-Hung Chen** Date: NOV 20 2015

Signature: Chien Hung Chen

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:	**Chun-Yuan Wu**	Date:	NOV 20 2015
Signature:	Chun-Yuan Wu		

Docket No NAUP2604USA

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Cheng-Tzung Tsai** Date: NOV 20 2015

Signature: Cheng-Tzung Tsai